

**Amendments to the Specification:**

Please replace paragraph number [0015] with the following:

[0015] It has been disclosed and claimed in U.S. patent application Serial No.09/259,142, assigned to the assignee of the present invention and issued as U.S. Patent No. 6,549,821, to modify a conventional stereolithography apparatus such as those offered by 3D Systems, Inc. with a machine vision system to precisely locate features on electronic components so as to enable fabrication of stereolithographic structures thereon. While a machine vision system enables fabrication of such structures on a large plurality of electronic components residing on a platform of a stereolithography apparatus and while a machine vision system may be employed to plot the gross (general) location and orientation of electronic components on a platform, such an approach may undesirably consume computer processing power as well as require a machine vision system employing two camera systems, one for determining the gross locations and orientations of the electronic components and another one for focusing on the surfaces, elements and features of an individual electronic component for precise placement of stereolithographic structures thereon. In addition, such an approach still requires handling of individual electronic components or electronic component assemblies to place same on the platform for fabrication of the stereolithographic structures and remove same after fabrication thereof for further processing. This necessity both enhances the potential for damage and contamination and inhibits automation of the stereolithography process for the described applications.

Please replace paragraph number [0035] with the following:

[0035] FIG. 1 depicts schematically various components, and operation, of an exemplary stereolithography apparatus 10 to facilitate the reader's understanding of the technology employed in implementation of the present invention, although those of ordinary skill in the art will understand and appreciate that apparatus of other designs and manufacture may be

employed in practicing the method of the present invention. A currently preferred, basic stereolithography apparatus for implementation of the present invention as well as operation of such apparatus is described in great detail in United States Patents assigned to 3D Systems, Inc. of Valencia, California, such patents including, without limitation, U.S. Patents 4,575,330; 4,929,402; 4,996,010; 4,999,143; 5,015,424; 5,058,988; 5,059,021; 5,096,530; 5,104,592; 5,123,734; 5,130,064; 5,133,987; 5,141,680; 5,143,663; 5,164,128; 5,174,931; 5,174,943; 5,182,055; 5,182,056; 5,182,715; 5,184,307; 5,192,469; 5,192,559; 5,209,878; 5,234,636; 5,236,637; 5,238,639; 5,248,456; 5,256,340; 5,258,146; 5,267,013; 5,273,691; 5,321,622; 5,344,298; 5,345,391; 5,358,673; 5,447,822; 5,481,470; 5,495,328; 5,501,824; 5,554,336; 5,556,590; 5,569,349; 5,569,431; 5,571,471; 5,573,722; 5,609,812; 5,609,813; 5,610,824; 5,630,981; 5,637,169; 5,651,934; 5,667,820; 5,672,312; 5,676,904; 5,688,464; 5,693,144; 5,695,707; 5,711,911; 5,776,409; 5,779,967; 5,814,265; 5,840,239; 5,854,748; 5,855,718; and 5,855,836. The disclosure of each of the foregoing patents is hereby incorporated herein by this reference. As noted in more detail below, however, a significant modification has been made to conventional stereolithography apparatus, such as those offered by 3D Systems, Inc., in the context of initiation and control of the stereolithographic disposition and fixation of materials. Specifically, the apparatus of FIG. 1 employs a so-called "machine vision" system in combination with suitable programming of the computer controlling the stereolithographic process, as disclosed and claimed in U.S. patent application Serial No. 09/259,142 filed February 26, 1999, now U.S. Patent No. 6,549,821, the disclosure of which patent is hereby incorporated herein by reference. Thus, the apparatus as described in FIG. 1 expands the use of stereolithography apparatus and methods to application of materials to large numbers of workpieces. While the workpieces employed may be, by way of example only, semiconductor dice, wafers, partial wafers, other substrates of semiconductor material or carrier substrates bearing integrated circuits on dice or other semiconductor structures, the method and apparatus of the invention are applicable to fabrication of other products.